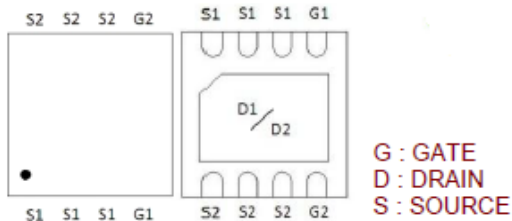


# PE5A0DZ

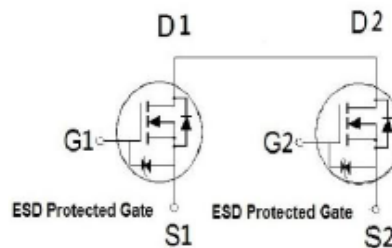
## Dual N-Channel Enhancement Mode MOSFET

### PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	$I_D$
20V	6m $\Omega$ @ $V_{GS} = 4.5V$	55A



PDFN 3X3S



### ABSOLUTE MAXIMUM RATINGS ( $T_A = 25\text{ }^\circ\text{C}$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS	SYMBOL	LIMITS	UNITS
Drain-Source Voltage	$V_{DS}$	20	V
Gate-Source Voltage	$V_{GS}$	$\pm 8$	
Continuous Drain Current <sup>2</sup>	$I_D$	$T_C = 25\text{ }^\circ\text{C}$	55
		$T_C = 100\text{ }^\circ\text{C}$	35
		$T_A = 25\text{ }^\circ\text{C}$	19
		$T_A = 70\text{ }^\circ\text{C}$	15
Pulsed Drain Current <sup>1</sup>	$I_{DM}$	100	A
Avalanche Current	$I_{AS}$	32	
Avalanche Energy	$E_{AS}$	51	mJ
Power Dissipation	$P_D$	$T_C = 25\text{ }^\circ\text{C}$	31
		$T_C = 100\text{ }^\circ\text{C}$	12.5
		$T_A = 25\text{ }^\circ\text{C}$	3.6
		$T_A = 70\text{ }^\circ\text{C}$	2.3
Operating Junction & Storage Temperature Range	$T_J, T_{stg}$	-55 to 150	$^\circ\text{C}$

### THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Ambient <sup>3</sup>	$R_{\theta JA}$		35	$^\circ\text{C} / \text{W}$
Junction-to-case	$R_{\theta JC}$		4	

<sup>1</sup>Pulse width limited by maximum junction temperature.

<sup>2</sup>Package limitation current is 18A.

<sup>3</sup>The value of  $R_{\theta JA}$  is measured with the device mounted on 1in2 FR-4 board with 2oz. Copper, in a still air environment with  $T_A = 25^\circ\text{C}$ .

# PE5A0DZ

## Dual N-Channel Enhancement Mode MOSFET

### ELECTRICAL CHARACTERISTICS (T<sub>J</sub> = 25 °C, Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNITS		
			MIN	TYP	MAX			
<b>STATIC</b>								
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA	20			V		
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA	0.4	0.7	1	V		
Gate-Body Leakage	I <sub>GSS</sub>	V <sub>DS</sub> = 0V, V <sub>GS</sub> = ±8V			±30	μA		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 16V, V <sub>GS</sub> = 0V			1	μA		
		V <sub>DS</sub> = 10V, V <sub>GS</sub> = 0V, T <sub>J</sub> = 125 °C			10			
Drain-Source On-State Resistance <sup>1</sup>	R <sub>DS(ON)</sub>	V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 3A	4	5	6	mΩ		
		V <sub>GS</sub> = 3.8V, I <sub>D</sub> = 3A	4.2	5.2	7.2			
		V <sub>GS</sub> = 3.1V, I <sub>D</sub> = 3A	4.5	5.6	7.8			
		V <sub>GS</sub> = 2.5V, I <sub>D</sub> = 3A	4.8	5.8	8			
		V <sub>GS</sub> = 1.8V, I <sub>D</sub> = 3A	7.2	8.7	12			
Forward Transconductance <sup>1</sup>	g <sub>fs</sub>	V <sub>DS</sub> = 5V, I <sub>D</sub> = 3A		43		S		
<b>DYNAMIC</b>								
Input Capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V, V <sub>DS</sub> = 10V, f = 1MHz		2111		pF		
Output Capacitance	C <sub>oss</sub>			320				
Reverse Transfer Capacitance	C <sub>rss</sub>			282				
Gate Resistance	R <sub>g</sub>	V <sub>GS</sub> = 0V, V <sub>DS</sub> = 0V, f = 1MHz		1.7		Ω		
Total Gate Charge <sup>2</sup>	Q <sub>g(VGS=4.5V)</sub>	V <sub>DS</sub> = 10V, I <sub>D</sub> = 3A		29		nC		
	Q <sub>g(VGS=3.9V)</sub>			25.5				
Gate-Source Charge <sup>2</sup>	Q <sub>gs</sub>			2.5				
Gate-Drain Charge <sup>2</sup>	Q <sub>gd</sub>			7.3				
Turn-On Delay Time <sup>2</sup>	t <sub>d(on)</sub>		V <sub>DD</sub> = 15V I <sub>D</sub> ≅ 3A, V <sub>GEN</sub> = 4.5V, R <sub>G</sub> = 6Ω		20			nS
Rise Time <sup>2</sup>	t <sub>r</sub>				40			
Turn-Off Delay Time <sup>2</sup>	t <sub>d(off)</sub>			72				
Fall Time <sup>2</sup>	t <sub>f</sub>			18				
<b>SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (T<sub>J</sub> = 25 °C)</b>								
Continuous Current <sup>3</sup>	I <sub>S</sub>				25.8	A		
Forward Voltage <sup>1</sup>	V <sub>SD</sub>	I <sub>F</sub> = 3A, V <sub>GS</sub> = 0V			1.2	V		
Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 3A, dI <sub>F</sub> /dt = 100A / μS		21		nS		
Reverse Recovery Charge	Q <sub>rr</sub>				8		nC	

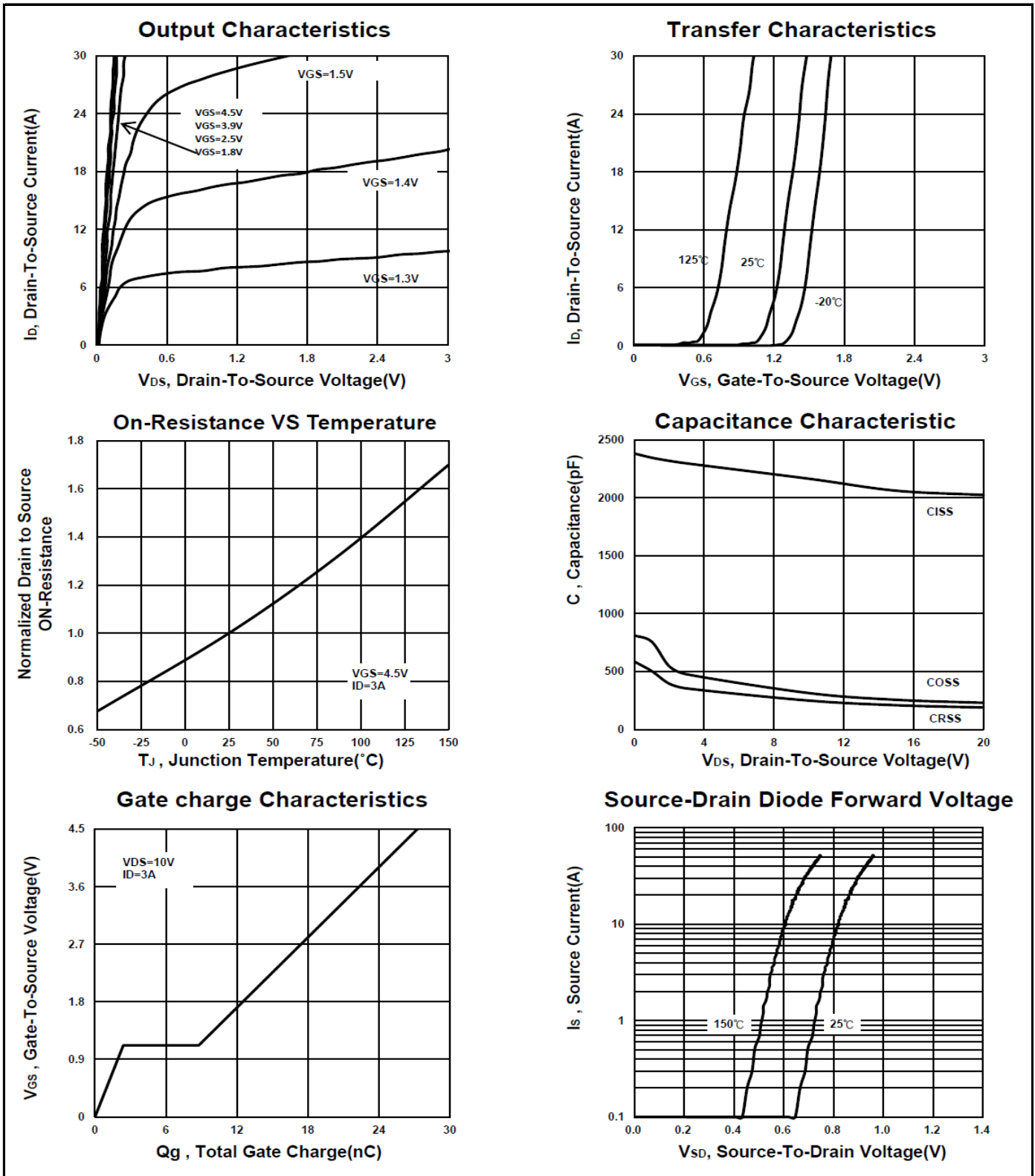
<sup>1</sup> Pulse test : Pulse Width ≤ 300 μsec, Duty Cycle ≤ 2%.

<sup>2</sup> Independent of operating temperature.

<sup>3</sup> Package limitation current is 18A.

# PE5A0DZ

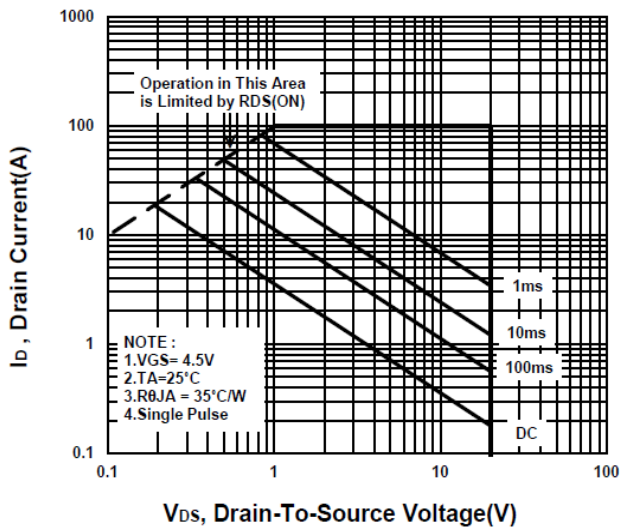
## Dual N-Channel Enhancement Mode MOSFET



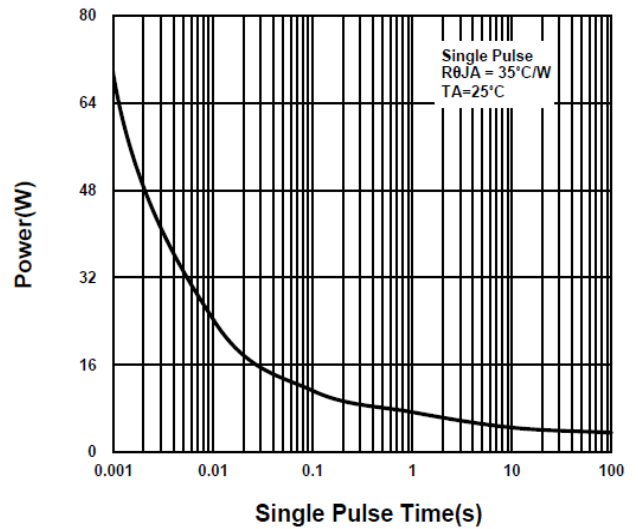
# PE5A0DZ

## Dual N-Channel Enhancement Mode MOSFET

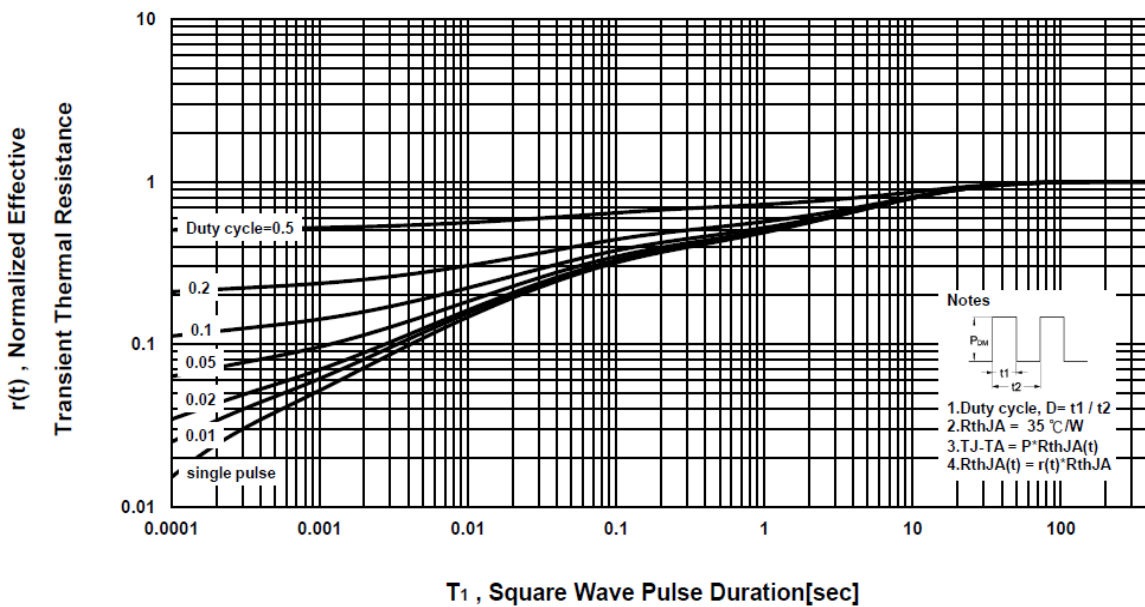
**Safe Operating Area**



**Single Pulse Maximum Power Dissipation**



**Transient Thermal Response Curve**



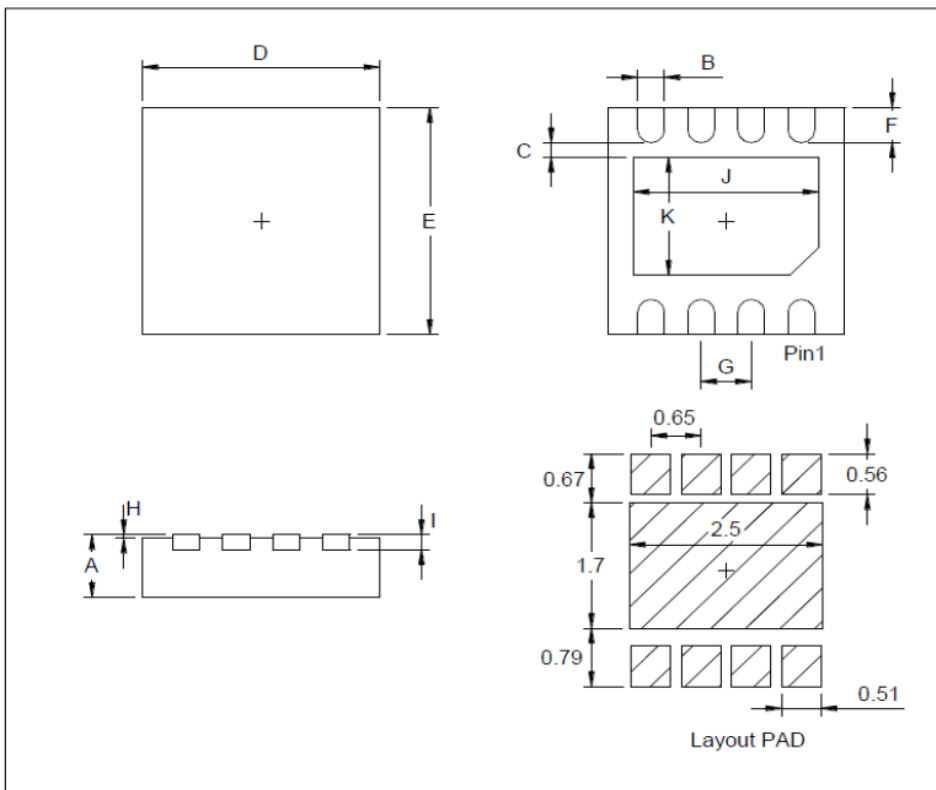
# PE5A0DZ

## Dual N-Channel Enhancement Mode MOSFET

### Package Dimension

### PDFN 3x3S MECHANICAL DATA

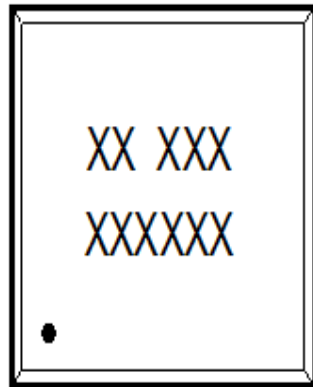
Dimension	mm			Dimension	mm		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	0.70		0.90	I	0.195		0.211
B	0.25		0.35	J	2.20		2.40
C	0.25		0.45	K	1.40		1.60
D	2.90		3.10				
E	2.90		3.10				
F	0.324		0.476				
G	0.55	0.65	0.75				
H	0		0.05				



# PE5A0DZ

## Dual N-Channel Enhancement Mode MOSFET

### A. Marking Information(此产品代码为: H2)

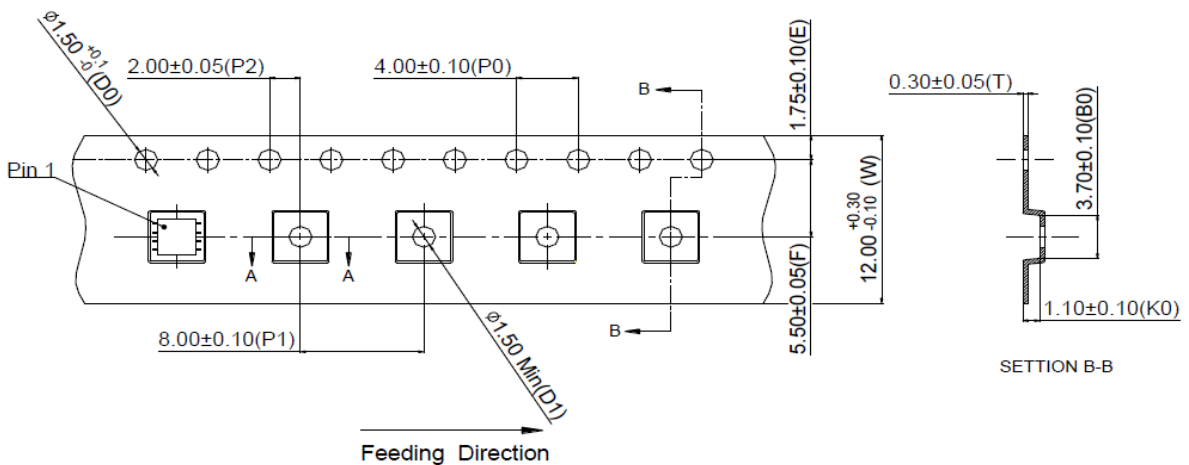


XX(前两码):产品代码

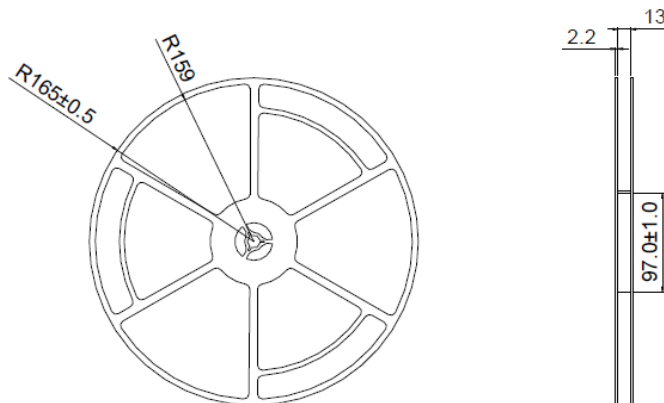
XXX

XXXXXX(后九码):LOT.NO

### B. Tape&Reel Information:5000pcs/Reel



SECTION B-B

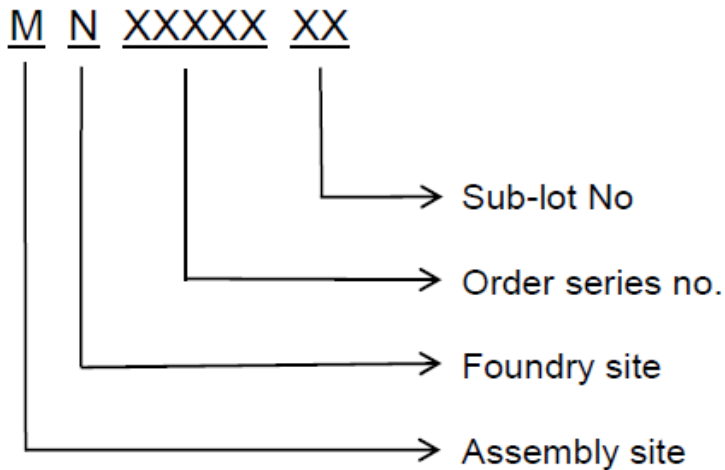


## PE5A0DZ

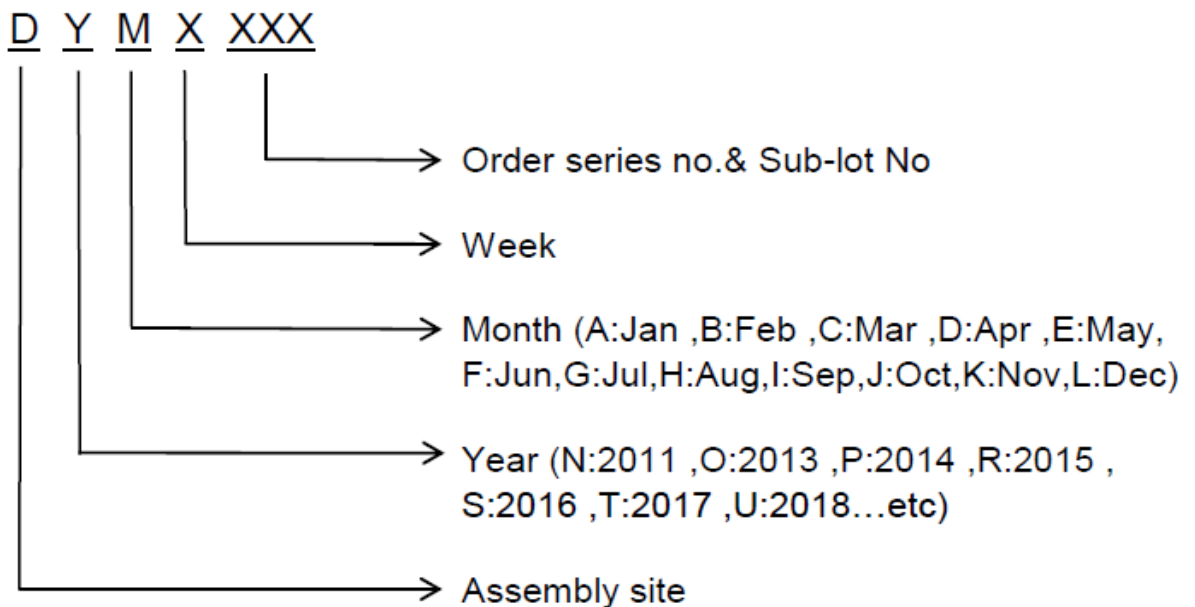
### Dual N-Channel Enhancement Mode MOSFET

#### C. Lot No.&Date Code rule

##### 1.Lot No.



##### 2.Date Code





## PE5A0DZ

### Dual N-Channel Enhancement Mode MOSFET

#### D.Label rule

标签内容(Label content)



1	Label Size	30 * 90 mm
2	Font style	Times New Roman or Arial (或可区分英文"0"和数字"0", "G"和"Q"的字型即可)
3	Great Power	Height: 4 mm
4	Package	Height: 2 mm
5	Date	Height: 2 mm Shipping date: YYYY/MM/DD, ex. 2008/09/12
6	Device	Height: 3 mm (Max: 16 Digit)
7	Lot	Height: 3 mm (Max: 9 Digit) Sub lot
8	D/C	Height: 3 mm (Max: 7 Digit)
9	QTY	Height: 3 mm (Max: 6 Digit) Thousand mark is no needed
10	Pb Free label	 Diameter: 1 cm bottom color: Green Font color: Black Font style: Arial
11	Halogen Free label	 Diameter: 1 cm bottom color: Green Font color: Black Font style: Arial
12	Scan info	Device / Lot / D/C / QTY , Insert " / " between every parts. for example: P3055LDG/G12345601/GGG2301/2000 DPI (Dots per inch): Over 300 dpi Code : Code 128 Height: 6 mm at least